



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-05-02
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giuseppe Vitali Palma	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
PD84008L-E	BEJZ*L5600Y1	A	SA1A	2017-05-02
Amount	UoM	Unit type	ST ECOPACK Grade	
69.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used c	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
QFF	4.90,4.90,0.80	14	flat	
Comment	VFQFPN Power Flat 14 5x5			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	BEIZ*LS600Y1						
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
Silicon Die	Other inorganic materials	2.567	mg	supplier	Silicon Die	Silicon (Si)	7440-21-3		2.511	mg	978185	36394	
Silicon Die				supplier	metallization	Aluminium (Al)	7429-90-5		0.053	mg	20647	768	
Silicon Die				supplier	back side metallization	Gold (Au)	7440-57-5		0.001	mg	390	14	
Silicon Die				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.002	mg	779	29	
Lead frame	Copper & its alloys	29.32	mg	supplier	alloy	Copper	7440-50-8		28.32	mg	965894	410435	
Lead frame				supplier	alloy	Iron	7439-89-6		0.661	mg	22544	9580	
Lead frame				supplier	alloy	Lead	7439-92-1		0.001	mg	34	14	
Lead frame				supplier	alloy	Phosphorus	7723-14-0		0.007	mg	239	101	
Lead frame				supplier	alloy	Zinc	7440-66-6		0.037	mg	1262	536	
Lead frame				supplier	alloy	Silver	7440-22-4		0.294	mg	10027	4261	
Die attach	Solder	0.235	mg	supplier	glue	Silver	7440-22-4		0.189	mg	804255	2739	
Die attach				supplier	glue	Carbocyclic Acrylate	Proprietary		0.024	mg	102128	348	
Die attach				supplier	glue	Bismaleimide resin	Proprietary		0.007	mg	29787	101	
Die attach				supplier	glue	2-preponoic acid, 2-methyl	68586-19-6		0.007	mg	29787	101	
Die attach				supplier	glue	Additive (1-5%)	Proprietary		0.007	mg	29787	101	
Die attach				supplier	glue	Dicumyl peroxide (0.1 - 1.0)	80-43-3		0.001	mg	4255	14	
Bonding wire	Other inorganic materials	0.952	mg	supplier	wire	Gold (Au)	7440-57-5		0.952	mg	1000000	13797	
Encapsulation	Other Organic Materials	34.16	mg	supplier	mold compound	Silica fused	60676-86-0		32.007	mg	936973	463870	
Encapsulation				supplier	mold compound	Epoxy resin	Proprietary		1.025	mg	30006	14855	
Encapsulation				supplier	mold compound	Phenol resin	Proprietary		1.025	mg	30006	14855	
Encapsulation				supplier	mold compound	Carbon black	1333-86-4		0.103	mg	3015	1493	
Finishing	Solder	1.766	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.766	mg	1000000	25594	